



Material Content Data Sheet



Sales Product Name		ICE5AR4770BZS		Issued		1. August 2018		
MA#		MA001731926						
Package		PG-DIP-7-5		Weight*		567.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	0.27	0.27	2673	2673
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		95	
	non noble metal	zinc	7440-66-6	0.215	0.04		379	
	non noble metal	iron	7439-89-6	4.297	0.76		7573	
wire	non noble metal	copper	7440-50-8	174.486	30.75	31.56	307477	315524
	noble metal	palladium	7440-05-3	0.001	0.00		2	
	non noble metal	copper	7440-50-8	0.118	0.02	0.02	209	211
encapsulation	organic material	carbon black	1333-86-4	3.765	0.66		6635	
	plastics	epoxy resin	-	71.541	12.61		126068	
	inorganic material	silicondioxide	60676-86-0	301.224	53.08	66.35	530812	663515
leadfinish	non noble metal	tin	7440-31-5	8.009	1.41	1.41	14114	14114
plating	noble metal	silver	7440-22-4	1.467	0.26	0.26	2585	2585
glue	plastics	epoxy resin	-	0.137	0.02		241	
	noble metal	silver	7440-22-4	0.645	0.11	0.13	1137	1378
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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